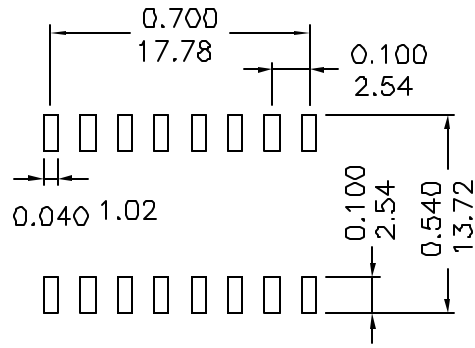
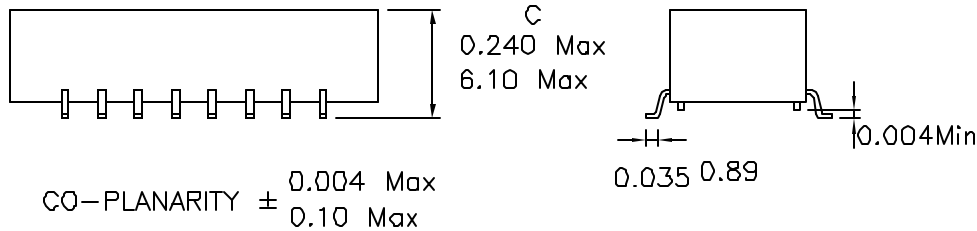
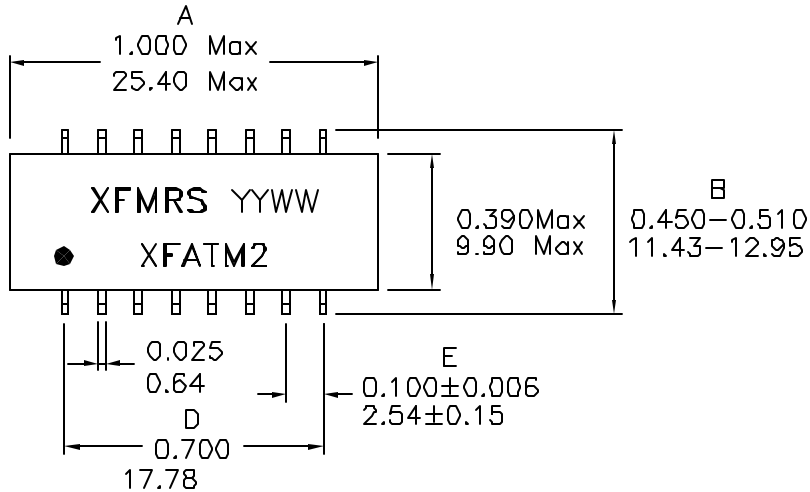


1. Dimensions:

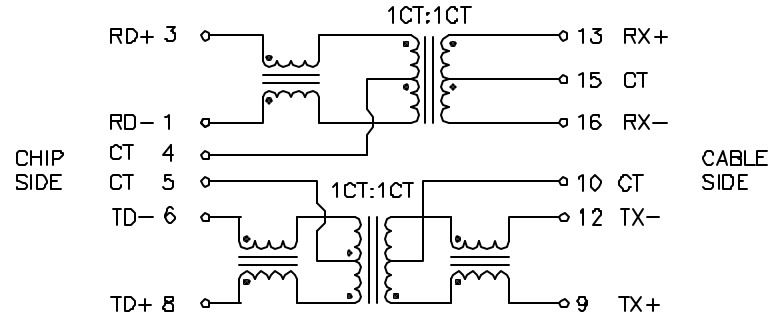


SUGGESTED FOOTPRINT

Notes:

1. Solderability: Leads shall meet MIL-STD-202, Method 208D for solderability.
2. Flammability: UL94V-0
3. ASTM oxygen index: > 28%
4. Insulation System: Class F 155°C, UL file E151556
5. Operating Temperature Range: All listed parameters are to be within tolerance from -40°C to +85°C
6. Storage Temperature Range: -55°C to +125°C
7. Aqueous wash compatible
8. SMD Lead Coplanarity: $\pm 0.004"$ (0.102mm)
9. Moisture Sensitivity: Level 2
10. Electrical and mechanical specifications 100% tested
11. RoHS Compliant Component

2. Schematic:



3. Electrical Specifications: @25°C

Isolation Voltage: 1500 Vrms (Input to Output)
 CHIP SIDE OCL: 350uH Minimum @100KHz 100mV 8mADC
 Rise Time (10-90%): 4.0ns Maximum
 Insertion Loss (100KHz-100MHz): -1.0dB Maximum
 Insertion Loss (100MHz-125MHz): -1.5dB Maximum
 Return Loss:
 Tx: @30MHz -20dB Typ Rx: @30MHz -18dB Typ
 @80MHz -15dB Typ @80MHz -12dB Typ
 CM-DM Attenuation:
 100KHz-60MHz -45dB Typ.(Tx) / -40dB Typ.(Rx)
 60MHz-100MHz -40dB Typ.(Tx) / -35dB Typ.(Rx)
 Crosstalk:
 100KHz-60MHz -40dB Typical
 60MHz-100MHz -38dB Typical

DOC.REV H/8

XFMRs Inc www.XFMRS.com		Title: HIGH SPEED LAN MAGNETICS	
UNLESS OTHERWISE SPECIFIED TOLERANCES: .xxx ± 0.010 Inch Dimensions in Inch/mm		P/N: XFATM2 REV. H	
		DWN. 罗振江	Nov-30-04
SCALE 2:1 SHT 1 OF 2		CHK. 廖玉坤	Nov-30-04
		APP. J Ng	Nov-30-04